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Organizations

On behalf of the Executive Committee of the IEA Heat Pump Programme, the Conference is organized by the National Organizing Committee (NOC):

John Tomlinson . . . Chairman, NOC
Melissa Lapsa Conference Secretariat
Don Bivens DuPont
Clark Bullard University of Illinois
Jim Crawford Trane
Phillip Fairchild . . . ORNL
Gerald Groff Groff Associates
Kim Grubb ORNL
Glenn Hourahan . . . Air Conditioning Contractors
of America
David Lewis Lennox
Nance Lovvorn Consultant
Wayne Reedy Carrier
John Ryan U.S. Department of Energy
Steve Szymurski . . . Air-Conditioning and
Refrigeration Institute

Exhibition

Space is available for an exhibition of heat pump hardware (manufacturers), R&D exhibits and information kiosks (heat pump associations, societies, and initiatives).

Participation

If you plan to attend the conference, please complete the attached reply card. Detailed information, including registration and hotel accommodation forms, will be sent together with a second announcement in Autumn 2004 to those persons who return the reply form. A program of cultural visits will be arranged for the accompanying persons.

General Information

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Email: hp2005@ornl.gov

Conference Internet Site:

<http://www.ornl.gov/hp2005>



Global Advances in Heat Pump Technology, Applications, and Markets

Las Vegas, Nevada, USA
30 May – 2 June 2005

First Announcement



Conference Venue and Dates

Las Vegas, Nevada continues to be one of the world's premier meeting and convention destinations while providing a gateway for families to explore the scenic southwest region of the United States. Las Vegas offers entertainment and activities day and night for attendees and their families such as top-name entertainment, world-class shopping and dining, more than 30 resort spas, nightclubs and lounges, and outdoor recreation at Lake Mead, Mt. Charleston, Red Rock Canyon, the Grand Canyon, and Hoover Dam. May temperatures average around 85°F (30°C) for the high and 60°F (15°C) for the low, with the humidity at 18%.

The conference will be held 30 May to 2 June, 2005, at Caesar's Palace Hotel in Las Vegas, Nevada. A welcoming reception will be held the evening of 30 May and technical visits will be arranged for the afternoon of 1 June.

Conference Goal

The goal of the conference is to promote the worldwide implementation and improvement of heat pump technologies via exchange and discussion of technical, market, policy, and standards information with respect to the environmental and energy-conserving benefits of these technologies.

Background and Approach

Heat pump technologies include heat pump, air conditioning and refrigeration equipment and

systems for residential, commercial, industrial, and district heating/cooling applications.

This conference is the eighth in a series of triennial conferences under the auspices of the International Energy Agency (IEA) Heat Pump Program. The conference will summarize the current technology and market status, progress, and trends. Previous conferences were held in Graz, Austria (1984), Orlando, USA (1987), Tokyo, Japan (1990), Maastricht, the Netherlands (1993), Toronto, Canada (1996), Berlin, Germany (1999), and Beijing, China (2002).

Who Should Attend

- Manufacturers and consultants
- R&D managers and equipment designers
- Policy makers and environmental analysts
- Executives from industry, utilities, and the public sector
- Educators and academic researchers

Conference Structure

The conference consists of

- Invited high level plenary and keynote speakers
- Oral presentations on the state-of-the-art in heat pump technology, applications, and markets
- Poster presentations of papers
- Exhibition of equipment and information kiosks
- Technical visits
- Social and sight-seeing program

The oral presentations are designed to provide international state-of-the-art summaries over a multi-year period. Invited keynote speakers will lead each major topical session. Poster

papers will supplement the oral presentations. Papers for oral and poster presentations are being solicited with this general call for papers. Submitted abstracts will be screened by a organizing committee to ensure that presentations complement the invited papers, stimulate discussion, and provide regional balance.

Conference Program

The conference program will include sessions on the following topics:

- ◆ Technology – Advances in equipment design and development
- ◆ Systems – Advanced electrically- and thermally-operated systems, and ground-source systems.
- ◆ Applications – Demonstrated energy efficiency and environmental advantages
- ◆ Policy, Standards, and Market Strategies – Government, utility, and professional society activities related to heat pumps.
- ◆ Markets – Market status, trends, and future opportunities
- ◆ International Activities – Discussion of actions in response to climate change initiatives.

Call for Papers

Abstracts (200 – 300 words) should be submitted to the appropriate Regional Coordinator listed on the reverse side by 1 April 2004. The abstracts will be screened and authors will be advised of acceptance by 1 June 2004. Full papers will be required by 1 December 2004.

8th IEA Heat Pump Conference **30 May – 2 June 2005, Las Vegas, Nevada**

(Please Print)

Mr/Mrs

Initials and Name

Institution

Mailing Address

Postal Code and City

State/Country

Telephone

Fax

Email

- I intend to participate in the conference; please send me the second announcement
- I intend to submit an abstract for consideration in the program.
- I intend to participate in the exhibition; please send me additional information.

Date

Signature

